

CUSTOM HYBRID PRODUCTS

(Request RCD Hybrid Catalog for complete information)

FEATURES

- Choice of thick-film or thin-film
- High volume specialist!
- SIP, DIP, or LCC packages
- Single or multilayer circuits
- Precision pattern accuracy to .005" line width and spacing
- Crossovers and through hole conductors available
- Surface Mount soldered or wire bonded
- Hermetic sealed construction available
- Wide choice of active and passive components
- Active or passive laser-trim capability



Over 30 years of hybrid experience!

As a thick film specialist, RCD had been supplying premetallized substrates to hybrid manufacturers for years. These substrates typically included all resistors as well as conductor paths and pads, ready for post assembly of additional active or passive components. RCD expanded its capability to include these post assembly operations and began offering completed hybrids in 1979. Typical savings up to 25% have been realized due to RCD's high volume automated production line. Our highly automated European and Far East affiliated factories, can offer the highest quality standards at the most economical price in the industry.

SPECIFICATIONS

Substrate: 96% Alumina (thick film circuits)
99% Alumina (thin film circuits)
FR-4 Glass Epoxy P.C. boards
Insulated Steel (thick film circuits)

Packaging: Conformal Coated
Epoxy Encapsulated
Hermetic Sealed
Ceramic Package

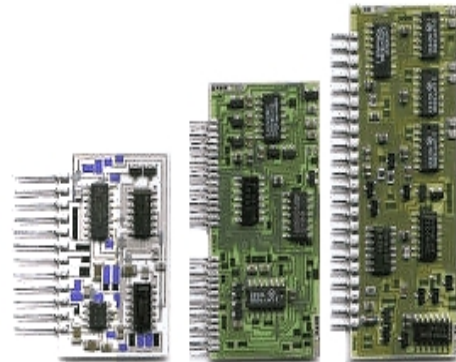
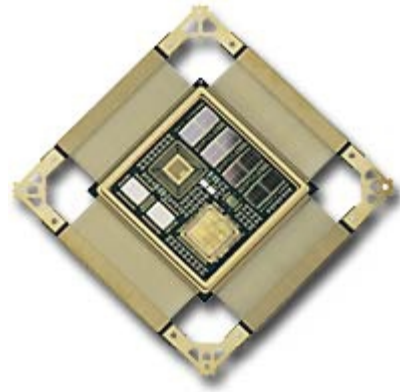
Resistors: Thin Film - 10 Ω to 1 Meg
Tolerances to 0.1%
TCR's to ± 5 ppm/ $^{\circ}$ C
Tracking to 2 ppm/ $^{\circ}$ C

Resistors: Thick Film - 0.5 Ω to 100 Gig (10¹¹ Ω)
Tolerances to 0.5%
TCR's to ± 50 ppm/ $^{\circ}$ C
Tracking to 25 ppm/ $^{\circ}$ C

Conductor: Material - Palladium Silver
Platinum Silver
Palladium Gold
Platinum Gold
Gold
Silver

Components: Active - Transistors
Diodes
Linear IC's
Digital IC's

Components: Passive - Capacitors
(Tantalum, Ceramic)
Inductors
Trimmers



SURFACE MOUNT SUBCONTRACT ASSEMBLY AVAILABLE!